Minutes of P-2.2 Committee on Aluminum, Film and Mica Capacitors

Tuesday, April 17, 2007 Holiday Inn San Diego Bayside San Diego, CA

Scope of the P-2.2 Committee on Aluminum, Film and Mica Capacitors

Attendees:

NAME		COMPANY
Mike	Griffith	KOA Speer
Mike	Lauri	IBM
Carl	Lindquist	SOC America, Inc.
Laird	Macomber	Cornell Dubilier
Dave	Ritchey	YAGEO Corp.
Jayson	Young	KEMET Inc.

1.0 Introductions
Chairman Laird Macomber called the meeting to order at 5:00 p.m.

2.0 Committee Organization and Procedures
2.1 Membership and Attendance
The roster was circulated and a quorum was present.

2.2 Approval of Agenda
The agenda was unanimously approved.

2.3 Approval of September 25, 2006, P-2.2 Subcommittee Meeting Minutes
The minutes were unanimously approved.

2.4 Correspondence
Mike Lauri read an email he had received from Terry Charles. Terry said that his company, Panasonic is no longer a member of EIA, and Panasonic representatives would no longer be attending meetings. He said that he would complete the draft of the SMT Film Capacitor Specification and provide it to Laird L Macomber.

2.5 Review of the Committee's Scope
Laird recommended that the scope be amended to allow moving solid-electrolyte aluminum electrolytic capacitors to the P-2.5 Subcommittee on Tantalum and Niobium Capacitors because the end market applications and construction of solid-electrolyte aluminum capacitors is quite similar to polymer cathode solid tantalum capacitors and the solid-tantalum capacitor makers are the ones making solid-aluminum capacitors. The

committee unanimously agreed providing that the P-2.5 Subcommittee accepts the transfer[1].

3.0 Reports

3.1 DSCC report

No reports.

4.0 Old Business

4.1 Status of SMT film capacitor specification.

Terry Charles has agreed to provide a draft to Laird. Laird will review with Chris Reynolds and present to the committee at the next meeting.

4.2 Results of Ballot for PN-4283 (EIA-797), Aluminum Electrolytic Capacitor Application Guideline

We received 3 approvals and comments from Cliff Zatz, but it is unknown what the comments were. Laird contacted Cliff Zatz but Cliff did not remember the comment. Ed Mikoski said that if Cliff rescinded his comment, we could publish. Laird sent a copy of Cliff Zatz's email of 10/16/06 withdrawing his comment and asked Cecelia to get EIA-797 published. At Ed Mikoski's request Laird sent another copy to Cecelia on 4/30/07.

4.3 Results of ballot for PN 4985, Aluminum Electrolytic Chip Capacitor with Polymer Cathode

PN4985 has been published as EIA 956

4.4 Results of ballot for PN 4984 Aluminum Electrolytic Capacitor Qualification Specification

Terry Charles has updated the document based on the minutes (In Section 1.3 delete the reference 57G9271 IBM Preconditioning Specification, and in Table 1, Method 4.8, Thermal Shock we should add asterisks (**) to indicate that three lots minimum are to be tested. This change makes the test method consistent with 4.4, 4.5 4.6 and 4.7). Terry agreed to send the document to Cecelia to be published as an EIA standard. On 4/30/07 Laird emailed Cecelia asking for a report.

4.7 Five-year Review of Documents.

4.7.1 Status archival of these documents:

EIA-376 Fixed Film Dielectric Capacitors in Metallic and Non-Metallic Cases, EIA 71, REAF 11/90

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[1] When the P-2.5 Subcommittee met at 2:00 p.m. on April 18th, the committee agreed to accept solid electrolyte aluminum capacitors at part of its scope and to expand the **EIA-809 Solid Tantalum Capacitor Application Guideline** to include both solid aluminum and niobium oxide capacitors. P-2.5 also agreed to move wet-tantalum dielectric capacitors to P-2.2. The new scope for P-2.5 is

Solid Electrolyte Capacitors Including Aluminum, Niobium and Tantalum

At the next P-2.2 meeting we'll vote to change the P-2.2 committee's name to

P-2.2 Committee on Film, Mica and Wet-electrolyte Capacitors

And change its scope to

Wet-electrolyte aluminum and tantalum capacitors and paper, film and mica capacitors excluding those for inductive heating and utility power-factor correction

EIA-395	Polarized Aluminum Electrolytic Capacitors, EIA 70, REAF 10/82
EIA-479 A	Film-Paper, Film Dielectric Capacitors for 50/60 Hz Voltage Doubler Power Supplies, EIA 5/93, ANSI 3/93
RS-361	Feed-Through Radio Interference Capacitors, Paper, Film, and Paper/Film Dielectric, EIA 1/69, ANSI 8/69
RS377	Metallized Dielectric Capacitors in Metallic and Non-Metallic, EIA 70, REAF 11/90
RS377-1	Parts List Supplement to RS-377, EIA 70, REAF 02/90

The committee requests that EIA confirm that the documents have been archived.

4.7.2 Status of revision of these documents:

EIA/IS-749	Rectified Mains Application Expected Wear-Out Lifetime Test, EIA 1/98
EIA-495-A	Film Dielectric Capacitors with Metallized Paper Electrodes for AC Applications, EIA 1/90, ANSI 11/89 REAF 5/97
EIA580A000	Sectional Specification for Fixed Chip Capacitors with Metallized Electrodes and Polyethylene-Terephthalate Dielectric for Use in Electronic Equipment, EIA 1/92, ANSI 11/91
EIA-580A0AC	Detail Specification for Fixed Metallized Polyethylene Terephthalate Film Dielectric, EIA 6/98
EIA-580A0AC	Detail Specification for Fixed Metallized Polyethylene Terephthalate Film Dielectric DC Capacitors Axial Leaded, EIA 6/98, ANSI 5/98
EIA-580AA00	Blank Detail Specification: Fixed Metallized Polyethylene-Terephthalate Film Chip Capacitors for DC – Encapsulated
EIA-580BA00	Blank Detail Specification: Fixed Metallized Electrode Film Dielectric AC Capacitors, EIA 10/97, ANSI 8/97
EIA-815	Miniature Aluminum Electrolytic Capacitor (Leaded) Qualification Specification, EIA 8/99
RS376	Fixed Film Dielectric Capacitors in Metallic and Non-Metallic Cases for DC Application, EIA 3/76, ANSI 7/71
RS376-1	Parts List Supplement to RS-376, Fixed Film Dielectric Capacitors inn Metallic and Non-Metallic Cases for DC Application, EIA 11/71, ANSI 9/72, EIA REAF 1990
RS401	Paper, Paper/Film, Film Dielectric Capacitors for Power Semiconductor Applications, EIA 3/73
RS454	Fixed Paper & Film-Paper Dielectric Capacitor, EIA 78, REAF 8/90

The committee request that EIA confirms that the documents have been archived.

5.0 New Business

Two issues: 1) Counterfeit SMD Lytic

2) Awareness of KFI development of Standards. Laird will contact Mark Cohen requesting a member of KFI to participate in the P-2.2 committee for writing standards.

Laird has contacted Mark Cohen and Mark has agreed to be involved with P-2.2

5.1 Review of P-2.2 time-slot and meeting length.

It was agreed at the All Committee Chairpersons meeting on April 18th that the next P-2.2 meet would be at the same point in the schedule but only an hour in length.

6.0 Next Meeting
The next meeting will be held September 25, 2007 at 5:00 p.m. at the Holiday Inn Riverwalk in San Antonio, TX.

7.0 Adjournment
The meeting was adjourned at approximately at 6:15 p.m.

This meeting was conducted in accordance with the EIA Legal Guidelines and the Manual of Organization and Procedures.

Laird Macomber

Laird Macomber
Chairman